

Claims

What is claimed:

1. A semiconductor device, comprising:
a drain electrode;
a source electrode;
a channel contacting the drain electrode and the source electrode, wherein the channel includes one or more of a metal oxide including zinc-germanium, zinc-lead, cadmium-germanium, cadmium-tin, cadmium-lead; and
a gate dielectric positioned between the gate electrode and the channel.
2. The semiconductor device of claim 1, wherein the channel includes one of an amorphous form, a single-phase crystalline form, and a mixed-phase crystalline form.
3. The semiconductor device of claim 1, wherein the metal oxide includes an atomic composition of metal(A)-to-metal(B) ratio (A:B), wherein A and B are each in a range of about 0.05 to about 0.95.
4. The semiconductor device of claim 1, wherein the metal oxide includes one or more of zinc-germanium oxide, zinc-lead oxide, cadmium-germanium oxide, cadmium-tin oxide, cadmium-lead oxide.
5. The semiconductor device of claim 4, wherein the metal oxide includes an atomic composition of metal(A)-to-metal(B) ratio (A:B), wherein A and B are each in a range of about 0.05 to about 0.95.
6. The semiconductor device of claim 1, wherein the channel includes one or more compounds of the formula $A_xB_xC_xO_x$, wherein each A is selected from the group of Zn, Cd, each B is selected from the group of Ge, Sn, Pb, each C is selected

from the group of Zn, Cd, Ge, Sn, Pb, each O is atomic oxygen, each x is independently a non-zero integer, and wherein each of A, B, and C are different.

7. The semiconductor device of claim 6, wherein the one or more compounds of the formula $A_xB_xC_xO_x$ includes an atomic composition of ratio A:B:C, wherein A, B, and C, are each in a range of about 0.025 to about 0.95.

8. The semiconductor device of claim 1, wherein the metal oxide includes one or more of zinc-germanium-tin oxide, zinc-tin-lead oxide, zinc-germanium-lead oxide, zinc-cadmium-germanium oxide, zinc-cadmium-tin oxide, zinc-cadmium-lead oxide, cadmium-germanium-tin oxide, cadmium-tin-lead oxide, cadmium-germanium-lead oxide.

9. The semiconductor device of claim 8, wherein the metal oxide includes an atomic composition or ratio A:B:C, wherein A, B, and C, wherein A, B, and C, are each in a range of about 0.025 to about 0.95.

10. The semiconductor device of claim 6, wherein the one or more compounds of formula $A_xB_xC_xO_x$, includes D_x , to form a compound of the formula $A_xB_xC_xD_xO_x$, wherein D is selected from the group of Zn, Cd, Ge, Sn, Pb, each O is atomic oxygen, each x is independently a non-zero integer, and wherein each of A, B, C, and D are different.

11. The semiconductor device of claim 10, wherein the one or more compounds of the formula $A_xB_xC_xD_xO_x$ includes an atomic composition of ratio A:B:C:D, wherein A, B, C, and D, are each in a range of about 0.017 to about 0.95.

12. The semiconductor device of claim 1, wherein the metal oxide includes one or more of zinc-germanium-tin-lead oxide, zinc-cadmium-germanium-tin oxide, zinc-cadmium-germanium-lead oxide, zinc-cadmium-tin-lead oxide, and cadmium-germanium-tin-lead oxide.

13. The semiconductor device of claim 12, wherein the metal oxide includes an atomic composition or ratio A:B:C:D, wherein A, B, C, and D, are each in a range of about 0.017 to about 0.95.
14. The semiconductor device of claim 10, wherein the one or more compounds of formula $A_xB_xC_xD_xO_x$ includes E_x , to form a compound of the formula $A_xB_xC_xD_xE_xO_x$, wherein E is selected from the group of Ge, Sn, Pb, each O is atomic oxygen, each x is independently a non-zero integer, and wherein each of A, B, C, D, and E are different.
15. The semiconductor device of claim 14, wherein the one or more compounds of the formula $A_xB_xC_xD_xE_xO_x$ includes an atomic composition of ratio A:B:C:D:E, wherein A, B, C, D, and E, are each in a range of about 0.013 to about 0.95.
16. The semiconductor device of claim 1, wherein the metal oxide includes one or more of zinc-cadmium-germanium-tin-lead oxide.
17. The semiconductor device of claim 16, wherein the metal oxide includes an atomic composition or ratio A:B:C:D:E, wherein A, B, C, D, and E, are each in a range of about 0.013 to about 0.95.
18. A semiconductor device, comprising:
a drain electrode;
a source electrode;
means for a channel to electrically couple the drain electrode and the source electrode; and
a gate electrode separated from the channel by a gate dielectric.
19. The semiconductor device of claim 18, wherein the means for a channel includes a means for forming one of an amorphous form, a single-phase crystalline form, and a mixed-phase crystalline form.

20. The semiconductor device of claim 18, wherein the source, drain, and gate electrodes include a substantially transparent material.
21. A method of forming a channel, comprising:
providing at least one precursor composition including one or more precursor compounds that include zinc oxide, cadmium oxide, germanium oxide, tin oxide, lead oxide, zinc-germanium oxide, zinc-lead oxide, cadmium-germanium oxide, cadmium-tin oxide, cadmium-lead oxide; and
depositing the channel including the precursor composition to form a multicomponent oxide from the precursor composition to electrically couple a drain electrode and a source electrode.
22. The method of claim 21, wherein depositing the channel includes depositing one of an amorphous form, a single-phase crystalline form, and a mixed-phase crystalline form.
23. The method of claim 21, wherein the precursor composition includes a liquid form.
24. The method of claim 23, wherein depositing the channel includes an ink-jet deposition technique when the precursor composition includes the liquid form.
25. The method of claim 21, wherein the precursor composition includes one or more precursor compounds that include A_x , one or more precursor compounds that include B_x , and one or more precursor compounds that include C_x , wherein each A is selected from the group of Zn, Cd, each B is selected from the group of Ge, Sn, Pb, each C is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, and C are different.

26. The method of claim 25, wherein the one or more precursor compounds includes one or more precursor compounds that include D_x , wherein each D is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, C, and D are different.
27. The method of claim 26, wherein the one or more precursor compounds includes one or more precursor compounds that include E_x , wherein E is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, C, D, and E are different.
28. The method of claim 21, wherein depositing the channel includes vaporizing the precursor composition to form a vaporized precursor composition, and depositing the vaporized precursor composition using a physical vapor deposition technique.
29. The method of claim 28, wherein the physical vapor deposition technique includes one or more of dc reactive sputtering, rf sputtering, magnetron sputtering, and ion beam sputtering.
30. A method of manufacturing a semiconductor device, comprising:
providing a drain electrode;
providing a source electrode;
step for providing at least one precursor composition including one or more precursor compounds that include: zinc oxide, cadmium oxide, germanium oxide, tin oxide, lead oxide, zinc-germanium oxide, zinc-lead oxide, cadmium-germanium oxide, cadmium-tin oxide, cadmium-lead oxide;
step for depositing a channel including depositing the precursor composition to form a multicomponent oxide from the precursor composition to electrically couple the drain electrode and the source electrode;
providing a gate electrode; and

providing a gate dielectric positioned between the gate electrode and the channel.

31. The method of claim 30, including providing a substrate or substrate assembly; and
forming the semiconductor device on the substrate or substrate assembly.

32. The method of claim 30, wherein the step for depositing a channel includes an ink-jet deposition technique.

33. The method of claim 30, wherein providing the source, the drain, and the gate electrodes includes providing a substantially transparent form of the source, the drain, and the gate electrodes.

34. The method of claim 30, wherein the precursor composition includes one or more precursor compounds that include A_x , one or more precursor compounds that include B_x , and one or more precursor compounds that include C_x , wherein each A is selected from the group of Zn, Cd, each B is selected from the group Ge, Sn, Pb, each C is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, and C are different.

35. The method of claim 34, wherein the one or more precursor compounds includes one or more precursor compounds that include D_x , wherein each D is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, C, and D are different.

36. The method of claim 35, wherein the one or more precursor compounds includes one or more precursor compounds that include E_x , wherein E is selected from the group of Zn, Cd, Ge, Sn, Pb each x is independently a non-zero integer, and wherein each of A, B, C, D, and E are different.

37. The method of claim 36, wherein the step for depositing a channel includes step for vaporizing the precursor composition to form a vaporized precursor composition, and depositing the vaporized precursor composition using a physical vapor deposition technique including one or more of dc reactive sputtering, rf sputtering, magnetron sputtering, and ion beam sputtering.

38. A semiconductor device formed by steps, comprising:
providing a drain electrode;
providing a source electrode;
providing a precursor composition that includes one or more precursor compounds that include: zinc oxide, cadmium oxide, germanium oxide, tin oxide, lead oxide, zinc-germanium oxide, zinc-lead oxide, cadmium-germanium oxide, cadmium-tin oxide, cadmium-lead oxide;
depositing a channel including the precursor composition to form a multicomponent oxide from the precursor composition to electrically couple the drain electrode and the source electrode;
providing a gate electrode; and
providing a gate dielectric positioned between the gate electrode and the channel.

39. The semiconductor device of claim 38, wherein the precursor composition includes one or more precursor compounds that include A_x , one or more precursor compounds that include B_x , and one or more precursor compounds that include C_x , wherein each A is selected from the group of Zn, Cd, each B is selected from the group Ge, Sn, Pb, each C is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, and C are different.

40. The semiconductor device of claim 39, wherein the one or more precursor compounds includes D_x , wherein each D is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, C, and D are different.

41. The semiconductor device of claim 40, wherein the one or more precursor compounds includes one or more precursor compounds that include E_x , wherein E is selected from the group of Zn, Cd, Ge, Sn, Pb, each x is independently a non-zero integer, and wherein each of A, B, C, D, and E are different.

42. The semiconductor device of claim 38, wherein depositing the channel includes vaporizing the precursor composition to form a vaporized precursor composition, and depositing the vaporized precursor composition using a physical vapor deposition technique including one or more of dc reactive sputtering, rf sputtering, magnetron sputtering, and ion beam sputtering.

43. The semiconductor device of claim 38, wherein providing the precursor composition includes providing a liquid form of the precursor composition.

44. The semiconductor device of claim 43, wherein depositing the channel includes an ink-jet deposition technique when the precursor composition includes the liquid form.

45. A method for operating a semiconductor device, comprising:
providing a semiconductor device that includes a source electrode a drain electrode, and a channel to electrically couple the source electrode and the drain electrode, a gate electrode separated from the channel by a gate dielectric, wherein the channel includes a multicomponent oxide selected from at least one metal cation from group 12, at least one metal cation from group 14, wherein group 12 cations include Zn and Cd, and group 14 cations include Ge, Sn, and Pb, to form at least one of a three-component oxide, a four-component oxide, a five-component oxide, and a two-component oxide that includes zinc-germanium oxide, zinc-lead oxide, cadmium-germanium oxide, cadmium-tin oxide, cadmium-lead oxide; and
applying a voltage to the gate electrode to effect a flow of electrons through the channel.

46. The method of claim 45, wherein operating the semiconductor device includes using the semiconductor device as a switch in a display device.
47. The method of claim 45, wherein operating the semiconductor device includes conducting electrons through the channel in a linear region of operation.
48. A display device, comprising:
a plurality of pixel devices configured to operate collectively to display images, where each of the pixel devices includes a semiconductor device configured to control light emitted by the pixel device, the semiconductor device including:
a drain electrode;
a source electrode;
a channel contacting the drain electrode and the source electrode, wherein the channel includes one or more of a metal oxide including: zinc-germanium oxide, zinc-lead oxide, cadmium-germanium oxide, cadmium-tin oxide, cadmium-lead oxide;
a gate electrode; and
a gate dielectric positioned between the gate electrode and the channel and configured to permit application of an electric field to the channel.
49. The display of claim 48, wherein the source, the drain, and the gate electrodes include a substantially transparent material.
50. The display of claim 48, wherein the metal oxide includes an atomic composition of metal(A)-to-metal(B) ratio (A:B), wherein A and B are each in a range of about 0.05 to about 0.95.
51. The display of claim 48, wherein the channel includes one or more compounds of the formula $A_xB_xC_xO_x$, wherein each A is selected from the group of

Zn, Cd, each B is selected from the group of Ge, Sn, Pb, each C is selected from the group of Zn, Cd, Ge, Sn, Pb, each O is atomic oxygen, each x is independently a non-zero integer, and wherein each of A, B, and C are different.

52. The display of claim 51, wherein the one or more compounds of the formula $A_xB_xC_xO_x$ includes an atomic composition of ratio A:B:C, wherein A, B, and C, are each in a range of about 0.025 to about 0.95.

53. The display of claim 51, wherein the one or more compounds of formula $A_xB_xC_xO_x$, includes D_x , to form a compound of the formula $A_xB_xC_xD_xO_x$, wherein D is selected from the group of Zn, Cd, Ge, Sn, Pb, each O is atomic oxygen, each x is independently a non-zero integer, and wherein each of A, B, C, and D are different.

54. The display of claim 53, wherein the one or more compounds of the formula $A_xB_xC_xD_xO_x$ includes an atomic composition of ratio A:B:C:D, wherein A, B, C, and D, are each in a range of about 0.017 to about 0.95.

55. The display of claim 53, wherein the one or more compounds of formula $A_xB_xC_xD_xO_x$ includes E_x , to form a compound of the formula $A_xB_xC_xD_xE_xO_x$, wherein E is selected from the group of Zn, Cd, Ge, Sn, Pb, each O is atomic oxygen, each x is independently a non-zero integer, and wherein each of A, B, C, D, and E are different.

56. The display of claim 55, wherein the one or more compounds of the formula $A_xB_xC_xD_xE_xO_x$ includes an atomic composition of ratio A:B:C:D:E, wherein A, B, C, D, and E, are each in a range of about .013 to about 0.95.

57. The display of claim 56, wherein the channel includes one of an amorphous form, a single-phase crystalline form, and a mixed-phase crystalline form.